

# **Sound Processors for Home Theater Systems**

# 6ch

# **Electronic Volume**



**BD3814FV** No.10081EAT05

#### Description

BD3814FV is a 1-chip sound processor incorporating such functions as volume, bass, and treble, necessary for AV receivers, home theater systems, and mini-audio systems. This IC adopts the Bi-CMOS process, and realizes low distortion, low noise, and a wide dynamic range.

#### Features

- 1) Dynamic range: 132dB (tone bypath, VOL = MUTE, IHF-A)
- 2) Master volume 6ch independent (0 to -95dB, MUTE 1dB/step)
- 3) Low current consumption design achieved by adopting the BiCMOS process
- 4) Maximum output voltage: 4.3Vrms (Vcc=7V, VEE=-7V, RL=10kΩ)
- 5) Built-in 2 OP amplifiers
- 6) 2-line serial control (for both 3.3V and 5V)

#### Applications

AV receivers, home theater systems, mini-audio systems, TVs etc.

#### ●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power supply voltage	VCC	7.5 <sup>*1</sup>	V
Power supply voltage	VEE	-7.5	V
Input signal voltage	VIN	VCC+0.3 to VEE-0.3	V
Power dissipation	Pd	900*2	mW
Operating temperature range	Topr	-20 to +75	°C
Storage temperature range	Tastg	-55 to +125	°C

<sup>\*1</sup> Even in the specified range of Power Supply Voltage, applying voltage only to the VCC side may cause an excessive current to give a permanent damage to the IC.

#### Operating conditions

Must function normally at Ta=25°C.

Parameter	Symbol		Ratings		Unit	
r didilletei	Symbol	Min.	Тур.	Max.	Offic	
Operating course voltage	VCC	5	7	7.3	\/	
Operating source voltage	VEE	-7.3	-7	-5	V	

When starting up power supplies, VEE and VCC should be powered on simultaneously or VEE first; then followed by VCC.

 $<sup>^{\</sup>star}2$  Reduced by 9 mW/°C over 25°C, when installed on the standard board (size: 70x70x1.6mm).

## • Electrical characteristics

Ta=25°C, VCC=7V, VEE=-7V, f=1kHz, Vin=1Vrms, RL=10k $\Omega$ , Rg=600 $\Omega$ , Master volume=0dB, Bass and Treble=0dB unless otherwise noted.

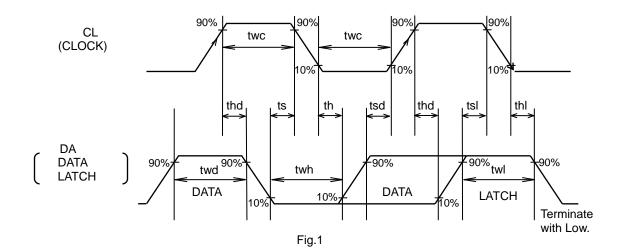
	Parameter		Symbol		Limits		- Unit.	Conditions
	Parami	eter	Symbol	Min.	Тур.	Max.	Unit.	Conditions
	Circuit current	VCC	- IQ	_	7	17	mA	No signal
	Circuit current	VEE	iQ	-17	-7		IIIA	No signal
	L input current(C	CL,DA)	IIL	_	0.5	5	μА	CL=DA=0V
	H input current(0	CL,DA)	IIH	_	0	5	μA	CL=DA=5V
	Output voltage g	ain 1	Gv1	-2	0	2	dB	Measure: Pin27,28,29,30, 31,32
	Output voltage g	ain 2	Gv2	-2	0	2	dB	Measure: Pin3, 7
	Total harmonic d	listortion	THD1	_	0.001	0.03	%	Measure: Pin27,28,29,30,31,32 BW=400 ~ 30kHz
	Total harmonic distortion ratio 2		THD2	_	0.001	0.03	%	Measure: Pin3, 7 BW=400 ~ 30KHz
ıtbut	Maximum output voltage 1		Vomax1	3.6	4.3	_	Vrms	Measure: Pin27,28,29,30,31,32 THD=1%
Total output	Maximum output	t voltage 2	Vomax2	3.6	4.3	_	Vrms	Measure: Pin 3,7 THD=1%
				_	1.0	6.0	μVrms	Measure: Pin 27, 28 Tone: By-pass, Rg=0Ω, BW=IHF-A
	Output noise vol	tage 1	Vno1	_	1.7	10	μVrms	Measure: Pin 27, 28 Tone: ON, Rg=0 Ω, BW=IHF-A
	Output noise vol	tage 2	Vno2	_	1.0	6.0	μVrms	Measure: Pin3, 7, 29, 30, 31, 32 Rg=0Ω, BW=IHF-A
	Cross talk between channels Rch→Lch		CTCRL	_	-95	-80	dB	Measure: Pin27(OUTFL) Rg=0Ω, BW=IHF-A Reference: Pin28(OUTFR)=1Vrms
	Cross talk between channels Lch→Rch		CTCLR	_	-95	-80	dB	Measure: Pin28(OUTFR) Rg=0 $\Omega$ , BW=IHF-A Reference: Pin27(OUTFL)=1Vrms
	Cross talk between channels SRch→SLch		CTCSRL	_	-95	-80	dB	Measure: Pin 30(OUTSL) Rg=0 $\Omega$ , BW=IHF-A Reference: Pin31(OUTSR)=1Vrms
	Cross talk between channels SLch→SRch		CTCSLR		-95	-80	dB	Measure: Pin 31(OUTSR) Rg=0 $\Omega$ , BW=IHF-A Reference: Pin30(OUTSL)=1Vrms
	Cross talk betwee Cch→SWch	CTCCSW	_	-95	-80	dB	Measure: Pin 32(OUTSW) Rg=0Ω, BW=IHF-A Reference: Pin29(OUTC) =1Vrms	

	Davamatav	Course had		Limits		Unit.	Conditions	
	Parameter	Symbol	Min.	Тур.	Max.	Offit.	Conditions	
	Input impedance V	RinV	14	20	26	kΩ	Measure: Pin27,28,29,30,31,32	
	Volume control range	GVR	-98	-95	-92	dB	Measure: Pin27,28,29,30,31,32 Vin=3Vrms	
	Volume set error 1	VE1	-1.5	0	1.5	dB	Measure: Pin27,28,29,30, 31,32 0 to -53dB, Vin=3Vrms	
Volume output	Volume set error 2	VE2	-2.5	0	2.5	dB	Measure: Pin27,28,29,30,31,32 -54 to -95dB, Vin =3Vrms	
Volume	Maximum attenuation amount	Vmin	_	-115	-105	dB	Measure: Pin27,28,29,30,31,32 Vin =3Vrms, BW=IHF-A	
	Residual noise voltage 1	Vnom1	_	1.0	6.0	μVrms	Measure: Pin27, 28 Tone: By-Pass, Rg=0 Ω , BW=IHF-A	
	Residual noise voltage 2	Vnom2	_	1.0	6.0	μVrms	Measure: Pin29, 30, 31, 32 Rg=0 Ω, BW=IHF-A	
	Cross talk between channels SWch→Cch	CTCSWC	_	-95	-80	dB	Measure: Pin 29(OUTC) Rg=0Ω, BW=IHF-A Reference: Pin32(OUTSW)=1Vrms	
	Treble maximum boost gain	GTB	12	14	16	dB	Measure: Pin 27, 28 f=15kHz, Vin =0.4Vrms	
Treble	Treble maximum cut gain	GTC	-16	-14	-12	dB	Measure: Pin 27, 28 f=15kHz, Vin =0.4Vrms	
Tre	Treble step resolution	TR	_	2	_	dB	Measure: Pin 27, 28 f=15kHz, Vin =0.4Vrms	
	Treble gain set error	TE	-2	0	2	dB	Measure: Pin 27, 28 f=15kHz, Vin =0.4Vrms	
	Bass maximum boost gain	GBB	12	14	16	dB	Measure: Pin 27, 28 f=100Hz, Vin=0.4Vrms	
Bass	Bass maximum cut gain	GBC	-16	-14	-12	dB	Measure: Pin 27, 28 f=100Hz, Vin =0.4Vrms	
Ba	Bass step resolution	BR	_	2	_	dB	Measure: Pin 27, 28 f=100Hz, Vin =0.4Vrms	
	Bass gain set error	BE	-2	0	2	dB	Measure: Pin 27, 28 f=100Hz, Vin =0.4Vrms	

<sup>\*</sup> Note: This IC is not designed to be radiation-resistant.

## ●Timing chart

- 1. Signal timing conditions
  - Data is read on the rising edge of the clock.
  - · Latch is read on the falling edge of the clock.
  - · Latch signal must terminate with the LOW state.
    - \* To avoid malfunctions, clock and data signals must terminate with the LOW state.



Parameter	Symbol			Unit		
Parameter	Symbol	Min.	Тур.	Max.	Offic	
Minimum clock width	twc	2.0	_	_	μs	
Minimum data width	twd	2.0	_	_	μs	
Minimum latch width	twl	2.0	_	_	μs	
LOW hold width	twh	2.0	_	_	μs	
Data setup time (DATA→CLK)	tsd	1.0	_	_	μs	
Data hold time (CLK→DATA)	thd	1.0	_	_	μs	
Latch setup time (CLK→LATCH)	tsl	1.0	_	_	μs	
Latch hold time (DATA→LATCH)	thl	1.0	_	_	μs	
Latch low setup time	ts	1.0	_	_	μs	
Latch low hold time	th	1.0	_	_	μs	

2. Voltage conditions for control signal

Parameter	Condition		Unit		
	Condition	Min.	Тур.	Max.(≦Vcc)	Offic
"H" input voltage	Vcc=5 ~ 7.3V	2.2	_	5.5	V
"L" input voltage	VEE=-5 ~ -7.3V	0	_	1.0	V

## 3. Basic configuration of control data format

← Data input direction

	MSB																LSB
	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Data							Da	ata							Sele	ct Add	ress

	<ul> <li>Control data format</li> <li>■ Data input direction</li> </ul>										Select Address						
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	Treble Bass							Tone	*	*	*	*	*	0	0	0	
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
2							Master Volume FLch						0	0	1		
Data	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
3								Master Volume SLch					0	1	0		
Data	D16 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 I						D5	D4	D3	D2	D1	D0					
4								N	Master	Volume	e SWcł	า		0	1	1	

By changing select address, 4 control data formats can be selected.

Do not set the select address data to any format other than that specified above.

At power-on sequence, initialize all data.

# Example:

◆ Data input direction



<sup>&</sup>quot;L" shows latch.

After power-on, for the second and subsequent times, only the necessary data can be selected for setting

Example: When to change bus,

Input direction

MSB LSB

Data① L

"L" shows latch.

<sup>\*</sup> is 0 or 1.

## Application circuit

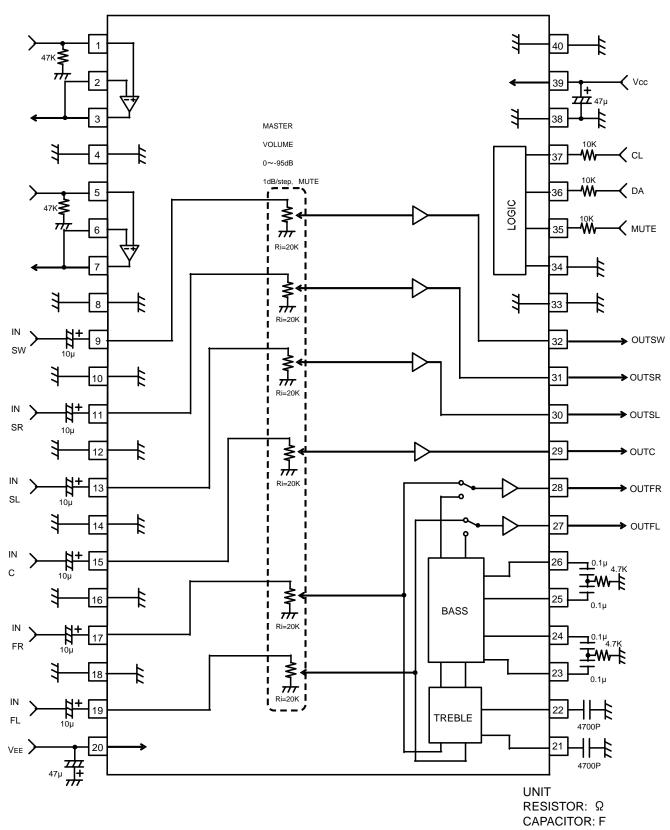


Fig.2

### ● Reference data

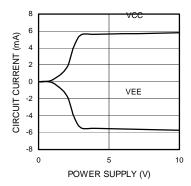


Fig.3 Circuit current - Power supply

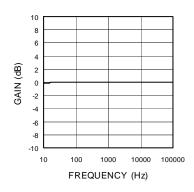


Fig.4 Voltage gain - Frequency

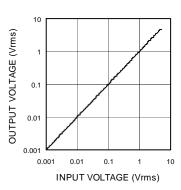


Fig.5 Output voltage - Input voltage

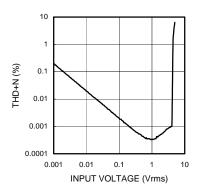


Fig.6 THD+N - Input voltage

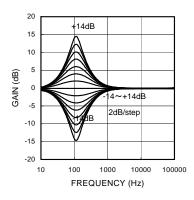


Fig.7 Bass gain - Frequency

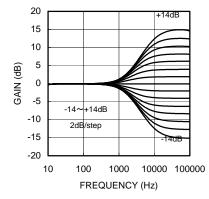


Fig.8 Treble gain - Frequency

BD3814FV Technical Note

#### Notes for use

- 1. Numbers and data in entries are representative design values and are not guaranteed values of the items.
- Although ROHM is confident that the example application circuit reflects the best possible recommendations, be sure to verify circuit characteristics for your particular application. Modification of constants for other externally connected circuits may cause variations in both static and transient characteristics for external components as well as this Rohm IC. Allow for sufficient margins when determining circuit constants.

#### 3. Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings, such as the applied voltage or operating temperature range (Topr), may result in IC damage. Assumptions should not be made regarding the state of the IC (short mode or open mode) when such damage is suffered. A physical safety measure, such as a fuse, should be implemented when using the IC at times where the absolute maximum ratings may be exceeded.

#### 4. VEE potential

Make the VEE pin voltage such that it is the lowest voltage even when operating below it. Actually confirm that the voltage of each pin does not become a lower voltage than the VEE pin, including transient phenomena.

#### 5. Thermal design

Perform thermal design, in which there are adequate margins, by taking into account the power dissipation (Pd) in actual states of use.

6. Short circuit between terminals and erroneous mounting

Pay attention to the assembly direction of the ICs. Wrong mounting direction or shorts between terminals, GND, or other components on the circuits, can damage the IC.

7. Operation in strong electromagnetic field

Using the ICs in a strong electromagnetic field can cause operation malfunction.

#### Serial control

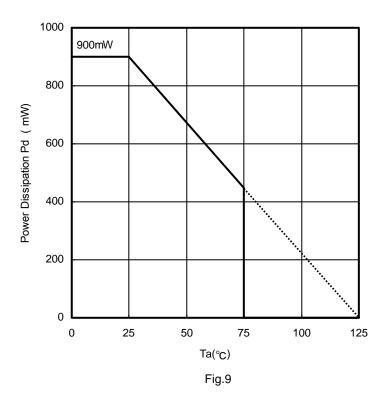
For the CL and DA terminals, the patterned and other wirings should be routed as not to cause interference with the analog-signal-related lines.

- 9. Power ON/OFF
  - (a) At power ON/OFF, a shock sound will be generated. Therefore, use MUTE on the set.
  - (b) When turning on power supplies, VEE and VCC should be powered on simultaneously, or VEE first followed by VCC. If the VCC side is started up first, an excessive current may flow from VCC to VEE.

#### 10. Tone bypath switching

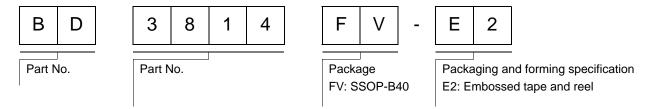
For tone bypath switching, use MUTE on the set.

# ●Thermal derating characteristic

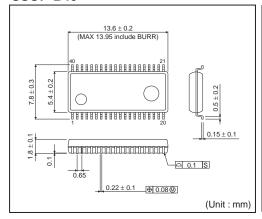


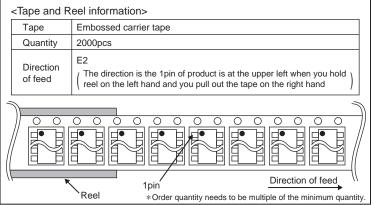
BD3814FV
ROHM standard board packaging time value
Board size: 70 x 70 x 1.6mm Raw material : FR4 glass epoxy board (copper area 3% or below)

## Ordering part number



## SSOP-B40





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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCTI
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
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  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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